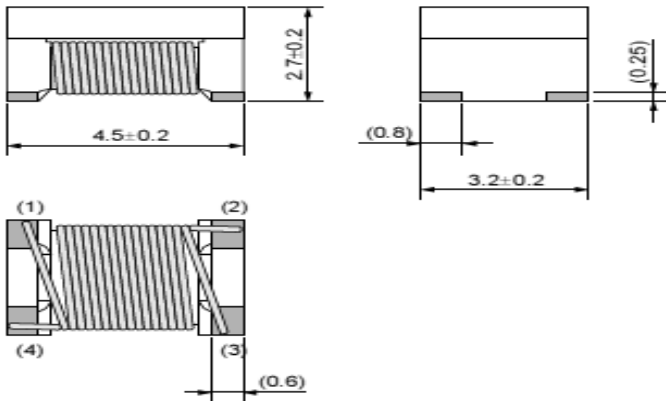


PACKING DIMENSIONS (mm)



| 4532 | Dimensions |
|------|------------|
| A | 4.5 ± 0.2 |
| B | 3.2 ± 0.2 |
| C | 2.7 ± 0.2 |
| D | 0.25 ± 0.1 |
| E | 0.8Typ. |
| F | 0.6Typ. |

ELECTRICAL CHARACTERISTICS

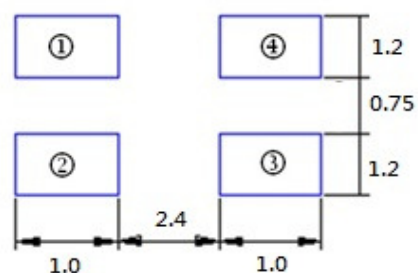
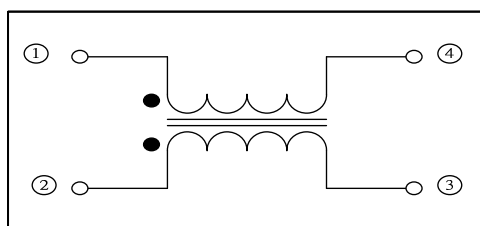
| P/N | L(μH) | DCR (Ω) | Idc(mA) | Rated Voltage | Insulation Resistance |
|----------------|----------------------|---------|---------|---------------|-----------------------|
| | Common Mode | | | Vdc | IR |
| | Inductance at 100KHz | [Max] | [Max] | (V)Typical | (MΩ)Min. |
| SMW4532S101XTT | (+50%/-30%) | 3.00 | 150 | 50 | 10 |
| | 100 | | | | |

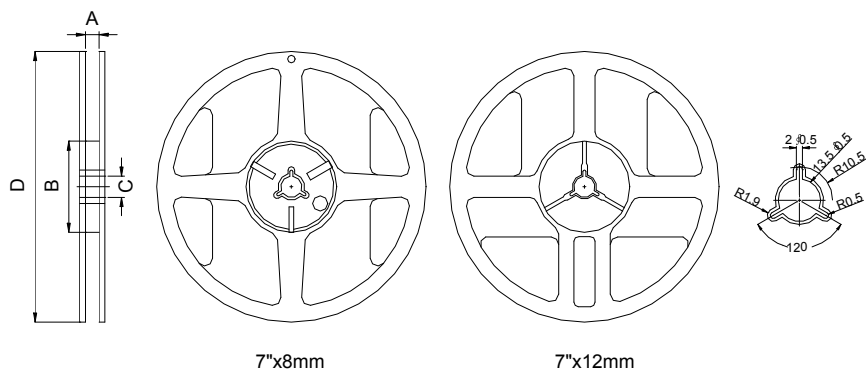
Operating temperature : -25 to +85°C

Storage temp. and humidity : -40 to +85°C ,70%RH max

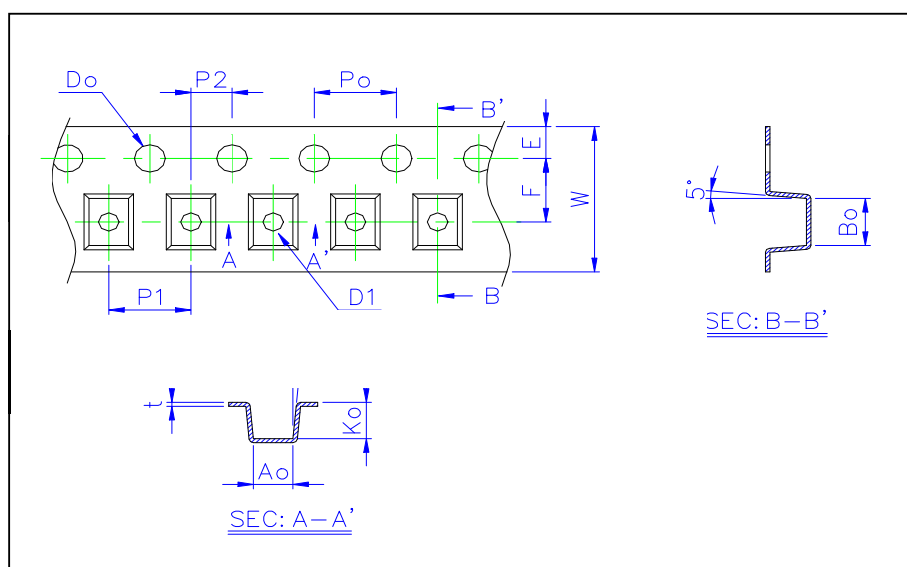
If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

Equivalent Circuit & Recommended Footprint



Reel Dimension & Tape Dimension


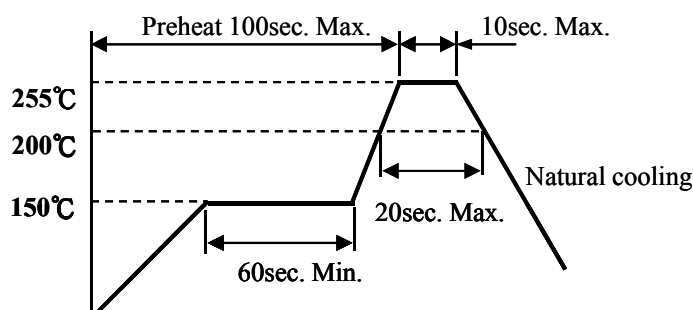
| Type | A(mm) | B(mm) | C(mm) | D(mm) |
|---------|----------|-------|----------|-------|
| 7"x8mm | 9.0±0.5 | 60±2 | 13.5±0.5 | 178±2 |
| 7"x12mm | 13.5±0.5 | 60±2 | 13.5±0.5 | 178±2 |

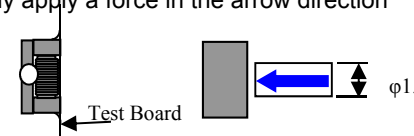


| Size | Ao(mm) | Bo(mm) | Ko(mm) | W(mm) | E(mm) | F(mm) | Po(mm) | P1(mm) | Do(mm) |
|------|-----------|-----------|-----------|------------|-----------|-----------|----------|----------|------------|
| 1210 | 1.15±0.10 | 1.40±0.10 | 0.93±0.10 | 8.00±0.20 | 1.75±0.10 | 3.50±0.05 | 4.0±0.05 | 4.0±0.10 | 1.5+0.1,-0 |
| 1608 | 1.65±0.10 | 1.00±0.10 | 1.18±0.10 | 8.00±0.20 | 1.75±0.10 | 3.50±0.05 | 4.0±0.05 | 4.0±0.10 | 1.5+0.1,-0 |
| 2012 | 2.35±0.10 | 1.50±0.10 | 1.45±0.10 | 8.00±0.20 | 1.75±0.10 | 3.50±0.05 | 4.0±0.05 | 4.0±0.10 | 1.5+0.1,-0 |
| 3216 | 3.50±0.10 | 1.88±0.10 | 2.10±0.10 | 8.00±0.20 | 1.75±0.10 | 3.50±0.05 | 4.0±0.05 | 4.0±0.10 | 1.5+0.1,-0 |
| 4532 | 3.45±0.10 | 4.90±0.10 | 3.05±0.10 | 12.00±0.20 | 1.75±0.10 | 5.50±0.05 | 4.0±0.05 | 8.0±0.10 | 1.5+0.1,-0 |

Packaging Quantity(Unit : PCS)

| Chip Size | 1210 | 1608 | 2012 | 3216 | 4532 |
|-----------|------|------|------|------|------|
| 8mm/ Reel | 3000 | 2000 | 2000 | 2000 | 500 |

RECOMMENDED SOLDERING TEMP. GRAPH

MECHANICAL RELIABILITY

| TEST | Specification & Requirement | | Method Used |
|------------------------|--|--------|---|
| Solderability | The surface of terminal/pin tested shall be covered with new solder by 90% | | Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 245 ±5°C for 4 ±1 sec |
| Solder Heat Resistance | Components should have not evidence of electrical and mechanical damage Impedance: within ±15% of initial value | | Preheating: 150°C 60secs Solder temperature: 260±5°C Flux: rosin Dip time: 10±0.5 secs |
| Terminal strength | Series No. | F (Kg) | Solder a chip to test substrate and then laterally apply a force in the arrow direction  |
| | SMW1210A/D | 0.2 | |
| | SMW1608A/C | 0.5 | |
| | SMW2012A/B/C | 0.5 | |
| | SMW3216A | 1.0 | |
| | SMW4532A | 1.0 | |

ENDURANCE RELIABILITY

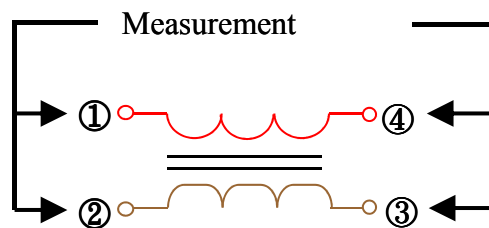
| TEST | Specification & Requirement | Method Used |
|---------------------|---|---|
| Thermal Shock | Impedance change within ± 15% Without mechanical damage | -65°C, (30 mins) -> room temp. (2 mins) -> 125°C, (30 mins) -> room temp. (2 mins) 50 cycles |
| Humidity Resistance | Impedance change within ± 15% Without mechanical damage | Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs |
| Low Temp. Storing | Impedance change within ± 15% Without mechanical damage | Storing Temp. -40 ±2 °C for total 168 +5/-0 hours |
| High Temp. Storing | Impedance change within ± 15% Without mechanical damage | Storing Temp. 125 ±2 °C for total 168 +5/-0 hours |

Test Equipment

Impedance / Inductance

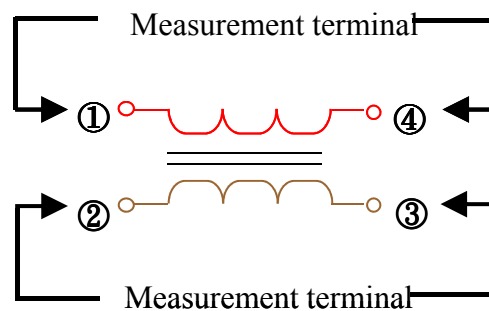
Measured by using Agilent 4291A RF Impedance Analyzer.

Measured by using Microtest 6377 LCR METER.



DC Resistance

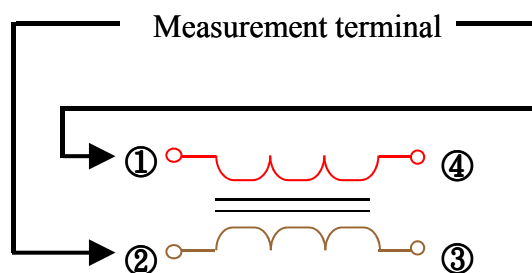
Measured by using Chroma 16502 mill ohm meter.



Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec.



PERFORMANCE CURVES

